

Inspection Sheet

1. Fundamental Dat

Wafer size	12"	Process	WAFER SCRUBBER
Model	SS 3000-AR	Manufacturing year	2007 , FEB
Maker	DNS	MFG. NO.	

2. Configuration of equipment

1) SYSTEM COMPOSITION

SS 3000-AR	4 BACK SIDE	
1	Load Port	3
2	INDEX UNIT	1
3	MAIN BODY	1
4	POWER BOX	1

2) GENERAL SPEC

WAFER	TYPE	THICKNESS	DIAMETER		
MAIN PRESSURE ALARM	DI ,AIR,EXH,N2,CO2				
PROCESS FORMULA					
BRUSH NOZZLE	UNIT-3,4,5,6				
N2 MASS FLOW	UNIT-3,4,5,6 NANO SPRAY Nozzle				
DI FILTER(4EA:0.05um)	UNIT-3,4,5,6				
SPIN CHUCK TYPE	MAGNETIC CHUCK TOTAL 6EA (LOCK,UN LOCK 2EA)				
WAFER SENSOR	WAFER DETECTOR SENSOR 4EA				
REVERSE UNIT	UNIT-7,8 REVERSE UNIT-1,2				
ULTRA SONIC FLOW METE	DIW, BACK RINSE, SPRAY NOZZLE, BRUSH RINSE				
E-FLOW	UNIT-3,4,5,6 NANO SPRAY Nozzle				
NANO SPRAY NOZZLE	1 NOZZLE				
DI RINSE NOZZLE	2 Front Rinse Nozzle				
DI BACK RINSE NOZZLE	1 BaCk Rinse Nozzle				

3)SYSTEM

HOST H/D	2 H/D
MAIN PC H/D	2 H/D
HUB BOX	2 H/D
LOAD PORT SENSOR	AREA SENSOR NO USE
IONIZER	INDEX POSITION

4. MISSING PART

5. Configuration

